CHIPQUIK®

SMD4300SNL250T3

Datasheet revision 1.6 www.chipquik.com

Solder Paste Water-Washable SAC305 in Jar 250g T3 Mesh

Product Highlights

Printing speeds up to 100mm/sec Long stencil life

Wide process window Clear residue

Excellent wetting compatibility on most board finishes
Print grade

Low voiding

Compatible with enclosed print heads
Passes BONO test @1.56%

RoHS 3 and REACH compliant

Applications

Suitable for most no-clean applications with or without cleaning. For applications requiring cleaning, use aqueous wash with appropriate saponification. Our SMD4300 series of fluxes and solder pastes are our easiest to clean, and have been used in many applications. Due to the wide range of applications and operating environments, customers should test this product in their specific application to ensure suitability.

Specifications

Alloy: Sn96.5/Ag3.0/Cu0.5

Mesh Size: T3
Micron (µm) Range: 25-45

Flux Type: Synthetic Water-Washable

Flux Classification: REL0

Metal Load: 88.75% Metal by Weight Melting Point: 217-220°C (423-428°F)

Packaging: Jar 250g

Shelf Life: Refrigerated >6 months, Unrefrigerated >2 months **See notes below:

**Shelf Life Notes: Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

Printer Operation

Print Speed: 25-100mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

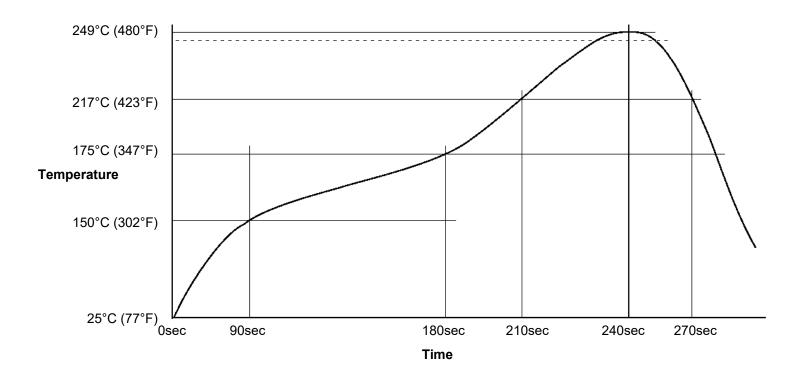
Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Recommended Profile

Reflow profile for Sn96.5/Ag3.0/Cu0.5 solder assembly, designed as a starting point for process optimization.



Test Results

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Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C,	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
85% RH @ 168 Hours		
Tack Value	IPC-TM-650: 2.4.44	37g
Viscosity – Malcom @ 10 RPM/25°C (x10³mPa/s)	IPC-TM-650: 2.4.34.4	Print: 155-215, Dispense: 80-115
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes